

# DIGITRON SEMICONDUCTORS

2N681-2N692, 2N5204-2N5207

SILICON CONTROLLED RECTIFIER

Available Non-RoHS (standard) or RoHS compliant (add PBF suffix).

Available as "HR" (high reliability) screened per MIL-PRF-19500, JANTX level. Add "HR" suffix to base part number.

## MAXIMUM RATINGS

| Rating  | Symbol       | 2N681-2N692 | 2N5204-2N5207 | Unit             |
|---|--------------|-------------|---------------|------------------|
| RMS on-state current                            | $I_{T(RMS)}$ | 25          | 35            | A                |
| Average on-state current                        | $I_{T(AV)}$  | 16          | 22            | A                |
| @ $T_c$   | $T_c$        | -65 to +65  | -40 to +40    | °C               |
| Peak one cycle surge @ 50 Hz                    | $I_{TSM}$    | 145         | 285           | A                |
| Peak one cycle surge @ 60 Hz                    |              | 150         | 300           | A                |
| Fusing @ 50 Hz                                  | $I^2t$       | 103         | 410           | A <sup>2</sup> s |
| Fusing @ 60 Hz                                  |              | 94          | 375           |                  |
| Gate current to trigger                         | $I_{GT}$     | 40          | 40            | mA               |
| Typical critical dv/dt exponential to $V_{DRM}$ | dv/dt        | -           | 100           | V/μs             |
| Critical rate of rise                           | di/dt        | 75-100      | 100           | A/μs             |
| Typical junction temperature                    | $T_j$        | -65 to 125  | -40 to 125    | °C               |

## VOLTAGE RATINGS (Applied gate voltage zero or negative)

| Part Number | $V_{RRM}, V_{DRM}$<br>Maximum repetitive peak reverse and off-state voltage (V) | $V_{RSM}$<br>Maximum non-repetitive peak reverse voltage $t_p \leq 5$ ms (V) |
|-------------|---|--|
|             | $T_j = -65$ to $+125^\circ\text{C}$   | $T_j = -65$ to $+125^\circ\text{C}$  |
| 2N681       | 25  | 35   |
| 2N682       | 50  | 75   |
| 2N683       | 100   | 150  |
| 2N685       | 200   | 300  |
| 2N687       | 300   | 400  |
| 2N688       | 400   | 500  |
| 2N689       | 500   | 600  |
| 2N690       | 600   | 720  |
| 2N691       | 700   | 840  |
| 2N692       | 800   | 960  |
|             | $T_j = -40$ to $125^\circ\text{C}$  | $T_j = -40$ to $125^\circ\text{C}$   |
| 2N5204      | 600   | 720  |
| 2N5205      | 800   | 960  |
| 2N5206      | 1000  | 1200   |
| 2N5207      | 1200  | 1440   |

## ELECTRICAL CHARACTERISTICS

| Symbol       | Characteristics  | 2N681-2N692 | 2N5204-2N5207 | Units            | Conditions   |   |
|--------------|--|-------------|---------------|------------------|--|---|
| $I_{T(RMS)}$ | Maximum RMS on-state current                           | 25          | 35            | A                | 180° half sine wave conduction                       |   |
| $I_{T(AV)}$  | Maximum average on-state current                       | 16          | 22            | A                |  |   |
| @ $T_c =$    |  | -65 to +65  | -40 to +40    | °C               |  |   |
| $I_{TSM}$    | Maximum peak one cycle, non-repetitive surge current   | 145         | 285           | A                | 50 Hz half cycle sine wave or 6 ms rectangular pulse | Following any rated load condition and with rated $V_{RRM}$ applied following surge |
|              |  | 150         | 300           |                  | 60 Hz half cycle sine wave or 5 ms rectangular pulse |   |
|              |  | 170         | 340           |                  | 50 Hz half cycle sine wave or 6 ms rectangular pulse | Same conditions as above except with $V_{RRM}$ applied following surge = 0          |
|              |  | 180         | 355           |                  | 60 Hz half cycle sine wave or 5 ms rectangular pulse |   |
| $I^2t$       | Maximum $I^2t$ capability, for fusing                  | 103         | 410           | A <sup>2</sup> s | t = 10 ms  | Rated $V_{RRM}$ applied following surge, initial $T_j = 125^\circ\text{C}$          |
|              |  | 94          | 375           |                  | t = 8.3 ms   |   |
| $I^2t$       | Maximum $I^2t$ capability for individual device fusing | 145         | 580           | A <sup>2</sup> s | t = 10 ms  | $V_{RRM} = 0$ following surge, initial $T_j = 125^\circ\text{C}$                    |
|              |  | 135         | 530           |                  | t = 8.3 ms   |   |

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## ELECTRICAL CHARACTERISTICS

| Symbol                    | Characteristics  | 2N681-2N692                                   | 2N5204-2N5207                        | Units         | Conditions   |                     |
|---------------------------|--|---|--------------------------------------|---------------|--|---------------------|
| $I^2\sqrt{t}$             | Maximum $I^2\sqrt{t}$ capability for individual device fusing <sup>(1)</sup>       | 1450  | 5800                                 | $A^2\sqrt{s}$ | $t = 0.1$ to 10ms initial $T_J \leq 125^\circ C$ , $V_{RRM}$ following surge = 0   |                     |
| $V_{TM}$                  | Maximum peak on-state voltage  | 2   | 2.3                                  | V             | $T_J = 25^\circ C$ , $I_{T(AV)} = 16A(50A \text{ peak})$ - 2N681<br>$I_{T(AV)} = 22A(70A \text{ peak})$ - 2N5204                                       |                     |
| $I_H$                     | Maximum holding current  | 20 @ 25°C                                     | 200 @ -40°C                          | mA            | Anode supply = 24V, initial $I_T = 1.0A$   |                     |
| <b>BLOCKING</b>           |  |   |                                      |               |  |                     |
| $dv/dt$                   | Minimum critical rate of rise of off-state voltage                                 | 100 typical                                   | 100                                  | $V/\mu s$     | $T_J = 125^\circ C$ exponential to 100% rated $V_{DRM}$  |                     |
|                           |  | 250 typical                                   | 250                                  |               | $T_J = 125^\circ C$ exponential to 67% rated $V_{DRM}$   |                     |
| $I_R^{(-)}$ & $I_D^{(-)}$ | Maximum reverse and off-state current  | $I_{R(AV)}$ & $I_{D(AV)}$<br>(average values) | $I_{RM}$ & $I_{DM}$<br>(peak values) | mA            | $T_J = 125^\circ C$ , gate open circuited  |                     |
|                           | $V_{RRM}$ & $V_{DRM} =$  | -   | -                                    |               |  |                     |
|                           | 25 to 150V   | 6.5   | -                                    |               |  |                     |
|                           | 200 & 250V   | 6.0   | -                                    |               |  |                     |
|                           | 300V   | 5.0   | -                                    |               |  |                     |
|                           | 400V   | 4.0   | -                                    |               |  |                     |
|                           | 500V   | 3.0   | -                                    |               |  |                     |
|                           | 600V   | 2.5   | 3.3                                  |               |  |                     |
|                           | 700V   | 2.25  | -                                    |               |  |                     |
|                           | 800V   | 2.0   | 2.5                                  |               |  |                     |
| 1000V                     | -  | 2.0   |                                      |               |  |                     |
| 1200V                     | -  | 1.7   |                                      |               |  |                     |
| <b>SWITCHING</b>          |  |   |                                      |               |  |                     |
| $t_d$                     | Typical delay time   | 1   | 1                                    | $\mu s$       | $T_C = 25^\circ C$ , $V_{DM} =$ rated $V_{DRM}$ , $I_{TM} = 10A$ dc resistive circuit. Gate pulse: 10 V, 40Ω source, $t_p = 6\mu s$ , $t_r = 0.1\mu s$ |                     |
| $di/dt$                   | Maximum non-repetitive rate of rise of turned-on current<br>$V_{DM} = 25$ to 600 V | 100   | -                                    | $A/\mu s$     | $T_C = 125^\circ C$ , $V_{DM} =$ rated $V_{DRM}$ , $I_{TM} = 2 \times di/dt$ , gate pulse: 20V, 15 Ω, $t_p = 6\mu s$ , $t_r = 0.1 \mu s$ maximum       |                     |
|                           | $V_{DM} = 700$ to 800 V  | 75  | -                                    |               |  |                     |
|                           |  | -   | 100                                  |               |  |                     |
| <b>TRIGGERING</b>         |  |   |                                      |               |  |                     |
| $P_{GM}$                  | Maximum peak gate power  | 5   | 60                                   | W             | $t_p \leq 5ms$ - 2N681<br>$t_p \leq 500\mu s$ - 2N5204   |                     |
| $P_{G(AV)}$               | Maximum average gate power   | 0.5   | 0.5                                  | W             |  |                     |
| $I_{GM}$                  | Maximum peak positive gate current   | 2   | 2                                    | A             |  |                     |
| $+V_{GM}$                 | Maximum peak positive gate voltage   | 10  | -                                    | V             |  |                     |
| $-V_{GM}$                 | Maximum peak negative gate voltage   | 5   | 5                                    | V             |  |                     |
| $I_{GT}$                  | Maximum required DC gate current to trigger  | 80  | 80                                   | mA            | $T_C =$ min rated value. Max. required gate trigger current is the lowest value which will trigger all units with 6V anode to cathode                  |                     |
|                           |  | 40  | 40                                   |               |  | $T_C = 25^\circ C$  |
|                           |  | 18.5  | 20                                   |               |  | $T_C = 125^\circ C$ |
|                           | Typical DC gate current to trigger   | 30  | 30                                   |               | $T_C = 25^\circ C$ , 6V anode to cathode   |                     |

Note 1:  $I^2t$  for time  $t_x \approx I^2\sqrt{t} \cdot \sqrt{t_x}$

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SILICON CONTROLLED RECTIFIER

## ELECTRICAL CHARACTERISTICS

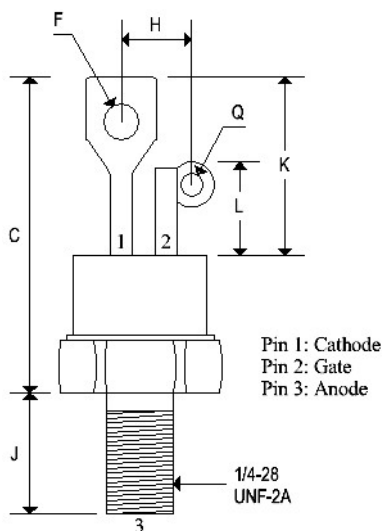
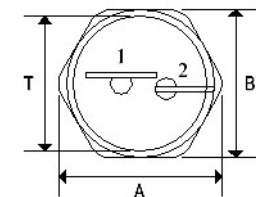
| Symbol   | Characteristics                             | 2N681-2N692 | 2N5204-2N5207 | Units | Conditions  |
|----------|---|-------------|---------------|-------|---|
| $V_{GT}$ | Maximum required DC gate voltage to trigger | 3           | 3             | V     | $T_C = -65^\circ\text{C}$ . Max. required gate trigger voltage is the lowest value which will trigger all units with 6V anode to cathode                |
|          | Typical DC gate voltage to trigger          | 1.5         | 1.5           |       | $T_C = 25^\circ\text{C}$<br>$T_C = 25^\circ\text{C}$ 6V anode to cathode  |
| $V_{GD}$ | Maximum DC gate voltage not to trigger      | 0.25        | 0.25          | V     | $T_C = 125^\circ\text{C}$ . Max. gate voltage not to trigger is the maximum value which will not trigger any unit with rated $V_{DRM}$ anode to cathode |

## THERMAL -MECHANICAL CHARACTERISTICS

| Symbol     | Characteristics                                       | 2N681-2N692 | 2N5204-2N5207 | Units                     | Conditions                                |
|------------|---|-------------|---------------|---------------------------|---|
| $T_J$      | Operating junction temperature range                  | -65 to 125  | -40 to 125    | $^\circ\text{C}$          |   |
| $T_{stg}$  | Storage temperature range                             | -65 to 125  | -40 to 125    | $^\circ\text{C}$          |   |
| $R_{thJC}$ | Maximum internal thermal resistance, junction to case | 1.5         | 1.5           | $^\circ\text{C}/\text{W}$ | DC operation                              |
| $R_{thCS}$ | Thermal resistance, case to sink                      | 0.35        | 0.35          | $^\circ\text{C}/\text{W}$ | Mounting surface smooth, flat and greased |

## MECHANICAL CHARACTERISTICS

|         |               |
|---------|---------------|
| Case    | TO-48         |
| Marking | Alpha-numeric |
| Pin out | See below     |

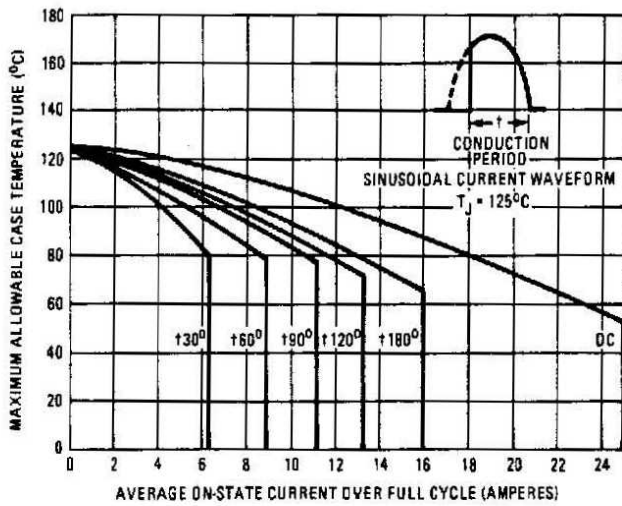


|   | TO-48  |       |             |        |
|---|--------|-------|-------------|--------|
|   | Inches |       | Millimeters |        |
|   | Min    | Max   | Min         | Max    |
| A | 0.604  | 0.614 | 15.340      | 15.600 |
| B | 0.551  | 0.559 | 14.000      | 14.200 |
| C | 1.050  | 1.190 | 2.670       | 30.230 |
| F | 0.135  | 0.160 | 3.430       | 4.060  |
| H | -      | 0.265 | -           | 6.730  |
| J | 0.420  | 0.455 | 10.670      | 11.560 |
| K | 0.620  | 0.670 | 15.750      | 17.020 |
| L | 0.300  | 0.350 | 7.620       | 8.890  |
| Q | 0.055  | 0.085 | 1.400       | 2.160  |
| T | 0.501  | 0.505 | 12.730      | 12.830 |

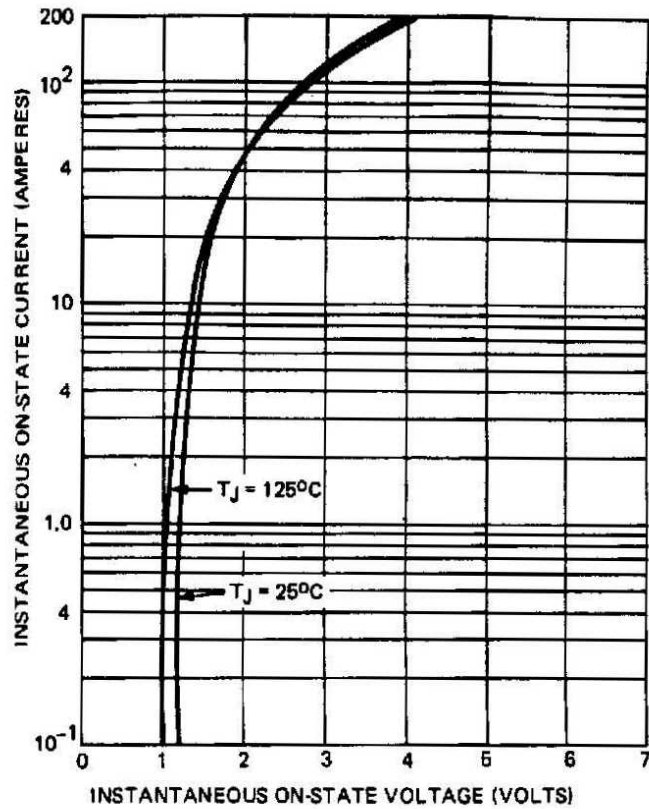
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## 2N681 Series



**Fig. 1 – Maximum Allowable Case Temperature Vs. Average On-State Current, 2N681 Series**



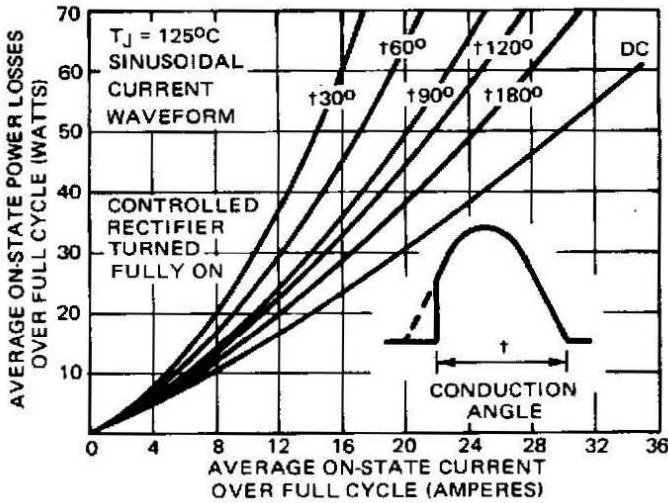
**Fig. 2 – Maximum On-State Voltage Vs. Current, 2N681 Series**

# DIGITRON SEMICONDUCTORS

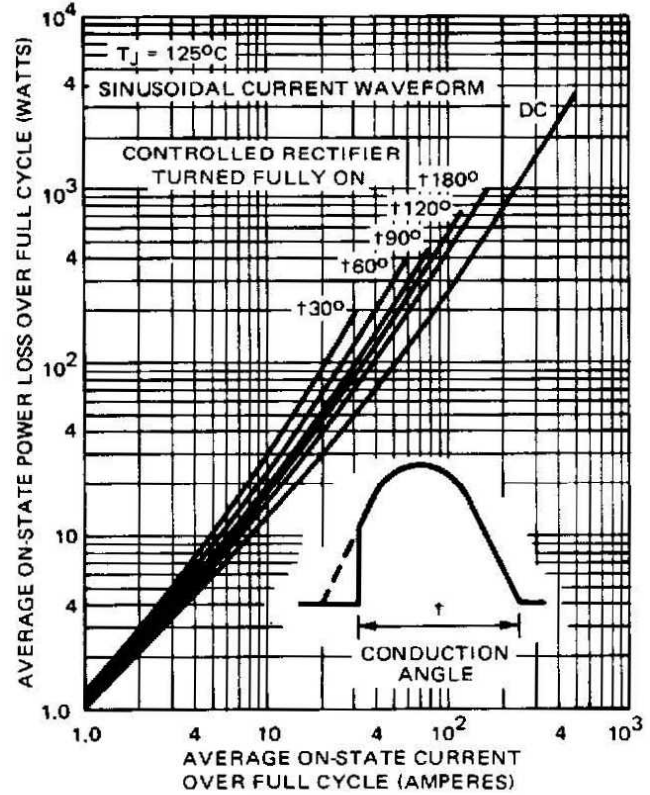
## 2N681-2N692, 2N5204-2N5207

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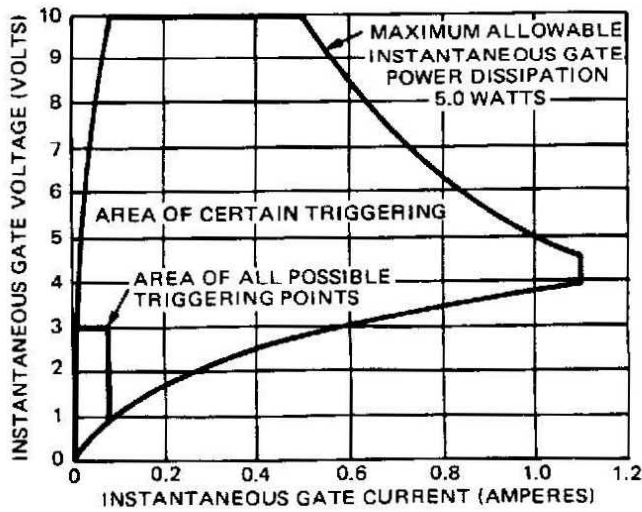
#### 2N681 Series



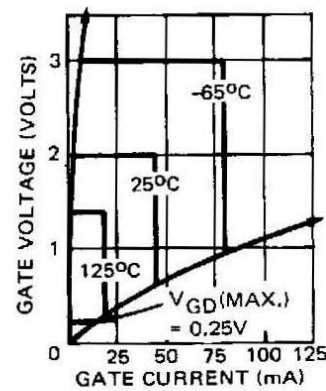
**Fig. 3 – Maximum Low Level On-State Power Loss Vs. Current (Sinusoidal Current Waveform), 2N681 Series**



**Fig. 4 – Maximum High Level On-State Power Loss Vs. Current (Sinusoidal Current Waveform), 2N681 Series**



**Fig. 5 – Gate Characteristics, 2N681 Series**

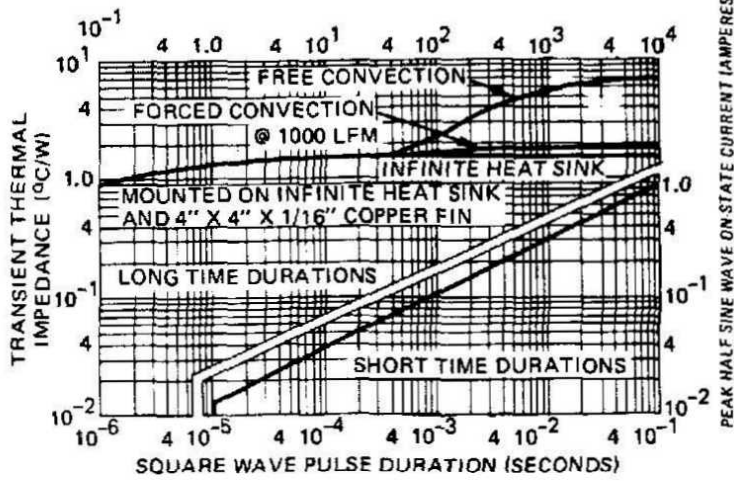


**Fig. 5A – Area of All Possible Triggering Points Vs. Temperature 2N681 Series**

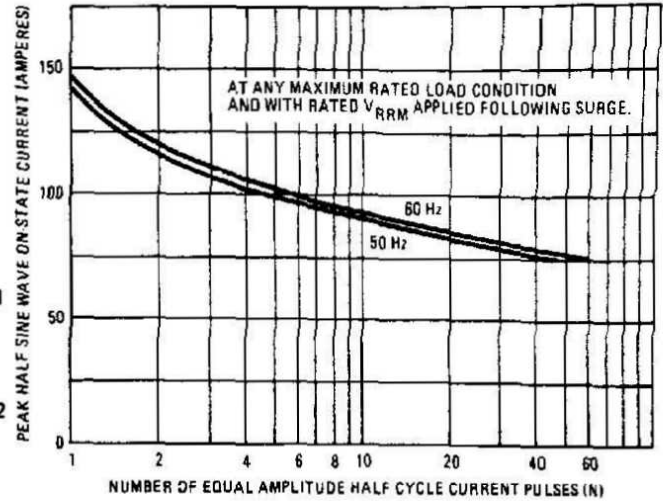
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## 2N681-2N692, 2N5204-2N5207

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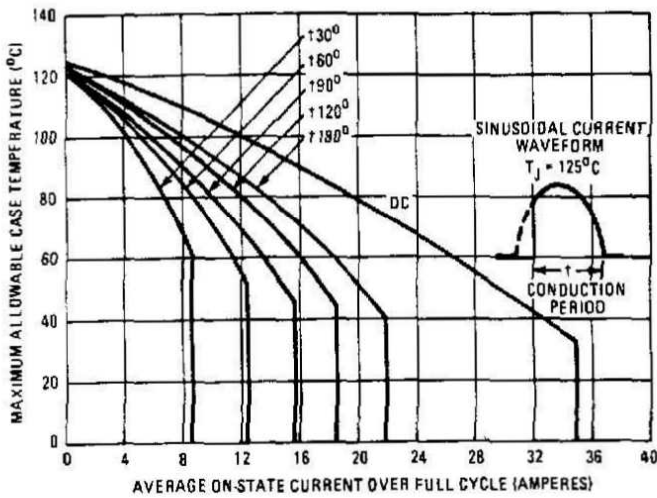


**Fig. 6 – Maximum Transient Thermal Impedance, Junction to Case, Vs. Pulse Duration, 2N681 Series**

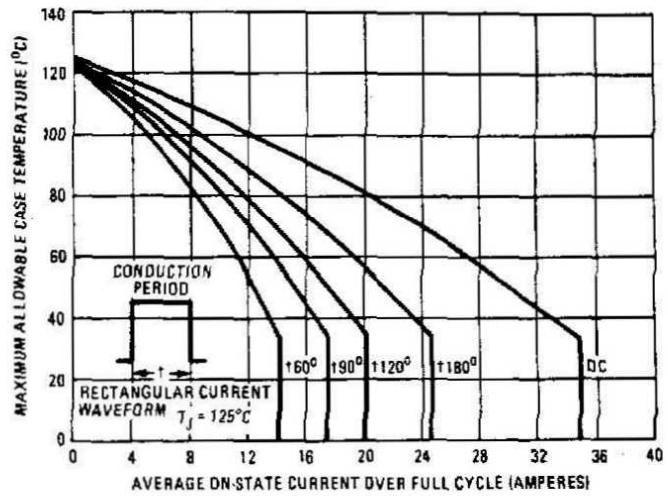


**Fig. 7 – Maximum Non-Repetitive Surge Current, Vs. Number of Current Pulses, 2N681 Series**

#### 2N5204 Series



**Fig. 8 – Maximum Allowable Case Temperature Vs. Average On-State Current (Sinusoidal Current Waveform), 2N5204 Series**



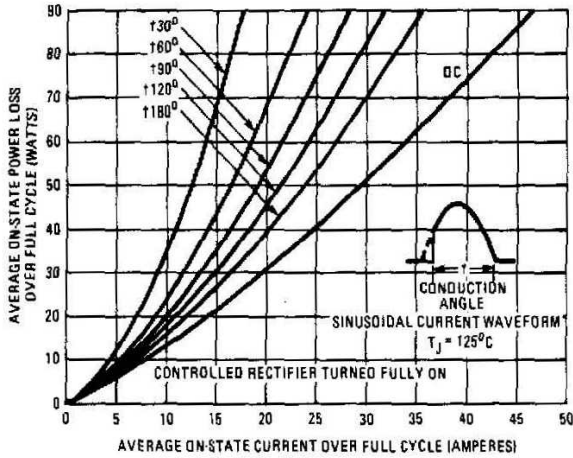
**Fig. 9 – Maximum Allowable Case Temperature Vs. Average On-State Current (Rectangular Current Waveform), 2N5204 Series**

# DIGITRON SEMICONDUCTORS

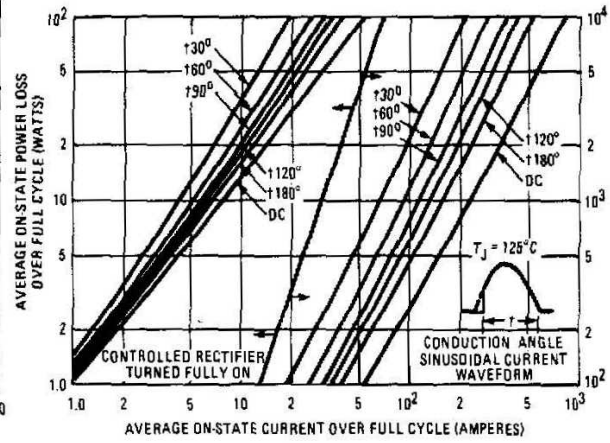
## 2N681-2N692, 2N5204-2N5207

### SILICON CONTROLLED RECTIFIER

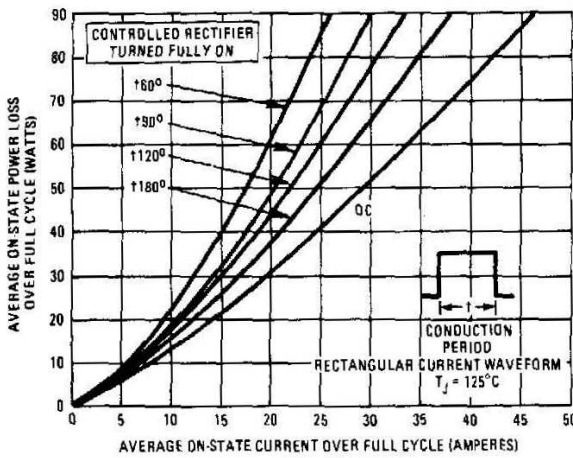
#### 2N5204 Series



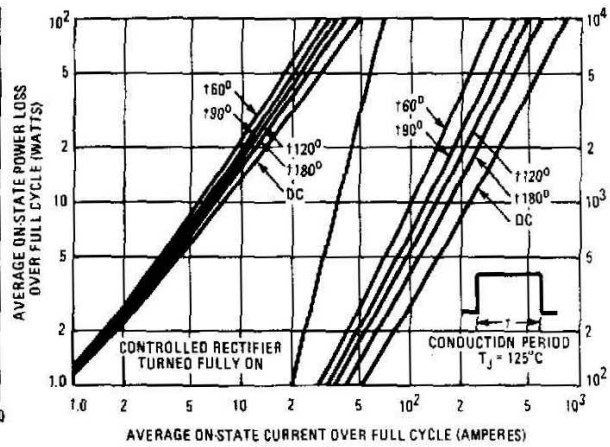
**Fig. 10 - Maximum Low-Level On-State Power Loss Vs. Average On-State Current (Sinusoidal Current Waveform), 2N5204 Series**



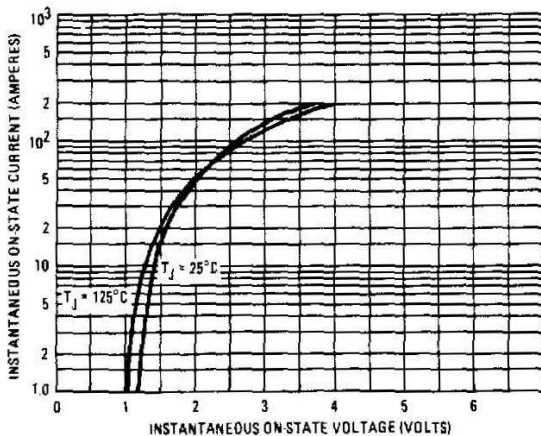
**Fig. 11 - Maximum High-Level On-State Power Loss Vs. Average On-State Current (Sinusoidal Current Waveform), 2N5204 Series**



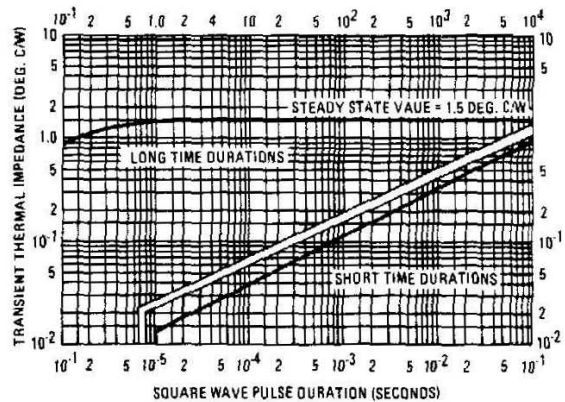
**Fig. 12 - Maximum Low-Level On-State Power Loss Vs. Average On-State Current (Rectangular Current Waveform), 2N5204 Series**



**Fig. 13 - Maximum High-Level On-State Power Loss Vs. Average On-State Current (Rectangular Current Waveform), 2N5204 Series**



**Fig. 14 - Maximum Instantaneous On-State Voltage Vs. Instantaneous On-State Current, 2N5204 Series**



**Fig. 15 - Maximum Transient Thermal Resistance, Junction to Case, Vs. Pulse Duration, 2N5204 Series**